SIP57 6.80x3.94
CASE 127EX
ISSUE B

DATE 10 MAR 2022
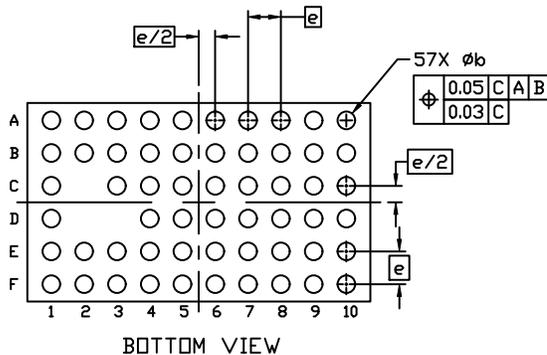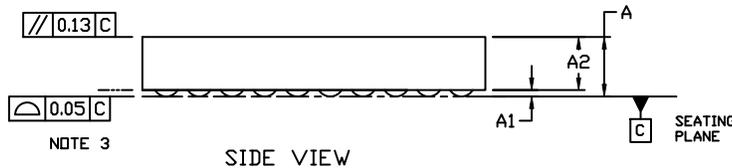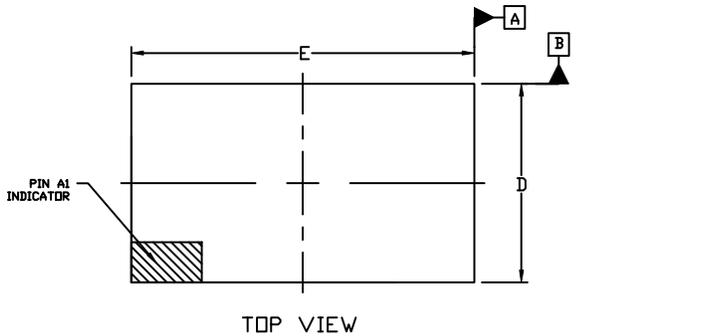
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

2. CONTROLLING DIMENSION: MILLIMETERS

3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE PADS.

TOP VIEW

PIN A1 INDICATOR

// 0.13 C

0.05 C
NOTE 3

SIDE VIEW

A2

A1

SEATING PLANE

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	1.275
A1	0.075	0.150
A2	1.025	1.125
b	0.300	0.400
D	3.815	4.065
E	6.675	6.925
e	0.650 BSC	

e/2

57X Øb

⊕ 0.05 C A B
   0.03 C

e/2

e

BOTTOM VIEW

0.650 PITCH

57X Ø0.356

0.650 PITCH

A1

RECOMMENDED MOUNTING FOOTPRINT
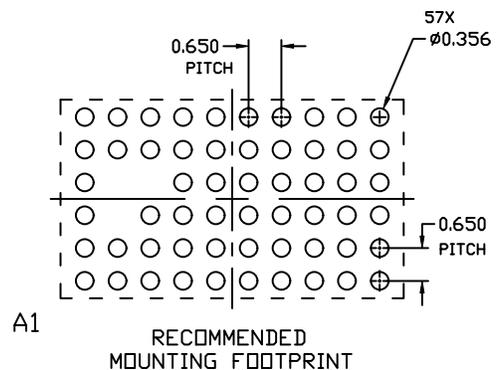
* For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

XXXXXXXXXXXX
ZZZZZZ
NNNNN
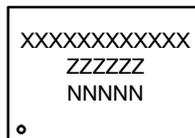
XXXX = Specific Device Code
ZZZ = Assembly Lot Code
NNN = Serial Number

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON80926G		
DESCRIPTION:	SIP57 6.80x3.94		PAGE 1 OF 1